

POWERSITE™ SURVEY

PowerSite pads allow the soldering of power devices directly to heat sinks with no attachment hardware. They offer excellent thermal performance and electrical isolation.

Please complete the following survey, and return this self-addressed and stamped card to EIS Fabrico. We will forward you a PowerSite prototype assembly and technical literature.

APPLICATION PROFILE	
Application description	_____ Power supply (AC/DC, DC/DC, inverter, UPS), Motion control, Motor control, etc.
Unit size	_____ Watts (power supply), Amps (motion control)
Design location(s) (specification)	_____ Ex., California, Germany, etc.
Manufacturing location(s)	_____ Ex., New Jersey, Taiwan, etc.
SUBASSEMBLY PROFILE	
Number of devices used annually (est.)	_____ TO-220
	_____ TO-247
	_____ Power module
	_____ Other
Waste heat per device (typical / peak)	_____/_____ _____ TO-220
	_____/_____ _____ TO-247
<p><u>NOTE:</u> EZ waste heat estimation formula: $WASTE\ HEAT\ per\ device = Power \times (100\% - Unit\ efficiency) / Number\ of\ power\ devices$ [NOTE: Device types = FET, diode, IGBT, etc.]</p>	
How many devices per heat sink?	_____
Are devices mounted on one or both sides of the heat sink?	_____
Attachment method	_____ Screw, clip, bar, etc.
Present interface material (Choose one or more)	_____ Pad type (please specify)
	_____ Other type (please specify)
	_____ Devices not electrically-isolated
	_____ Case-isolated devices used (ex., Iso-Pak)

Biggest concerns about subassembly (in order of priority, 1=highest)	_____	Device temperature
	_____	Electrical isolation integrity
	_____	Labor cost and consistency
Power device failures now mainly due to.....	_____	
How would you use the improvement in thermal performance? (in order of priority 1-6, 1=highest)	_____	Cooler power device (same part number)
	_____	Run unit at higher power, with same devices
	_____	Cheaper power device (different part number)
	_____	Less devices in assembly (assuming parallel operation)
	_____	Higher ambient rating of unit
_____	Smaller heat sink	
NEW TECHNOLOGY ADOPTION		
Would you consider PowerSite technology for...?	_____	Existing design
	_____	New design under development
	_____	Future design
How long does your company require to....?	_____	Qualify new technology (months)
	_____	Design=>commercialization
	_____	Introduce new unit (conceptualization=>market)
POWERSITE SUPPLY CHAIN		
Your supply preference: (in order 1-3, 1=highest)	_____	Buy turn-key subassemblies, including devices and heat sinks
	_____	Provide devices+heat sinks for toll conversion into subassemblies
	_____	Do own PowerSite assembly in-house

Mail the completed survey to EIS Fabrico and receive:

- PowerSite prototype samples (TO-220s soldered to aluminum heat sink)
- PowerSite technical bulletin on thermal performance
- PowerSite technical bulletin on bond durability
- PowerSite product brochure

No purchase necessary.